FU CHUN SHIN MACHINERY MANUFACTURE CO., LTD.
(6603)

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Tel：06-5950688#8877
E-mail:YING@fcs.com.tw

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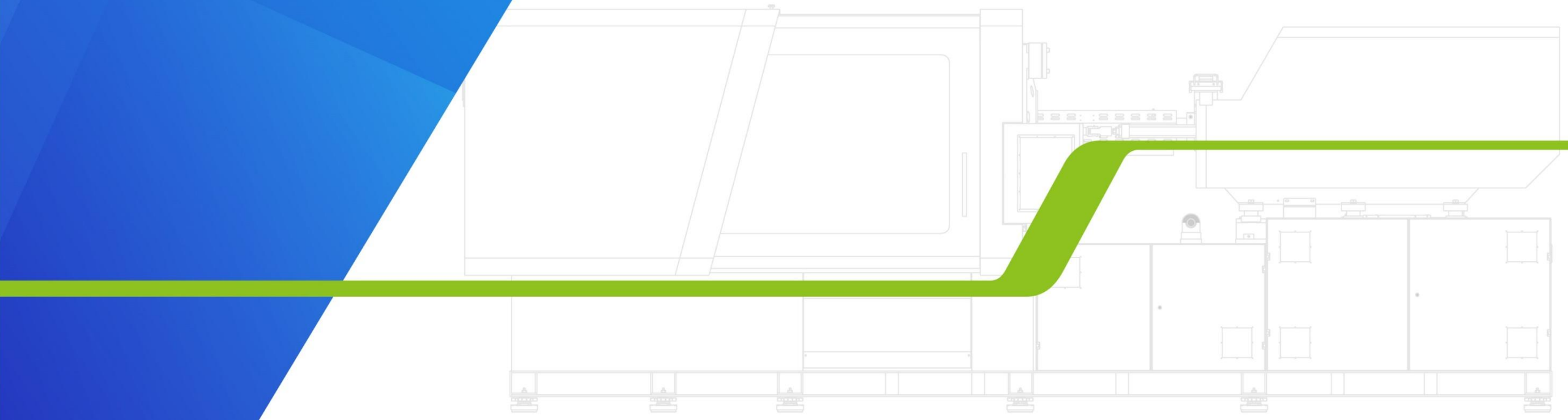
Table of Contents

1. Company Profile
2. Market Opportunities
3. Products & Customers
4. Competitive Advantages
5. Business Review
6. Next Growth Curve

PART 01

Company Profile

Provider of Injection Molding Solutions



About FCS

NT$5.08 Billion
2025 Group Revenue
Record High

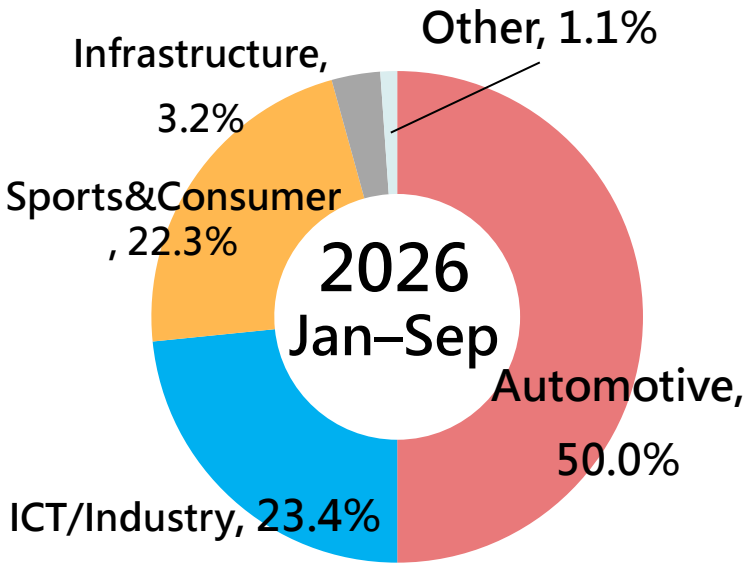
950+
Employees Worldwide
Professional Team · Innovation-Driven Growth

5
Manufacturing Facilities
57 Global Service Locations
36 Direct Offices · 21 Distributor Locations

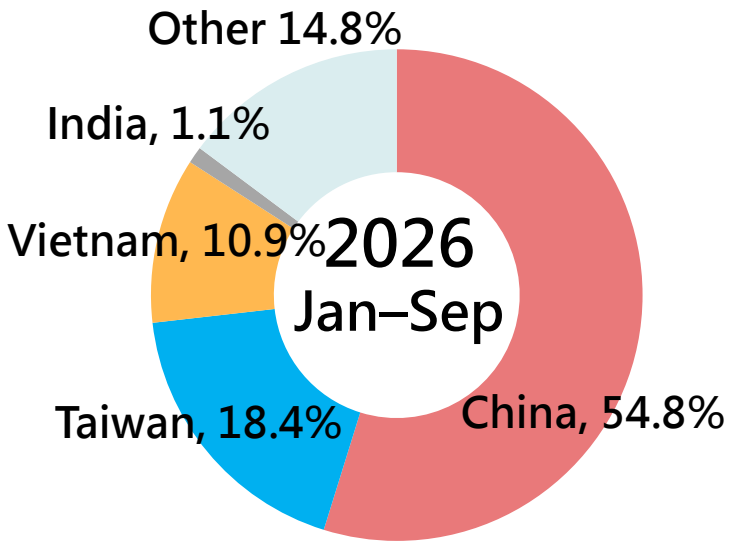
Ranked No. 578 in Manufacturing
Taiwan Institute of Directors
2026 High-Potential Mittelstand Enterprise

R&D Investment: **3%** of Revenue
Committed to Innovation · Driving the Future

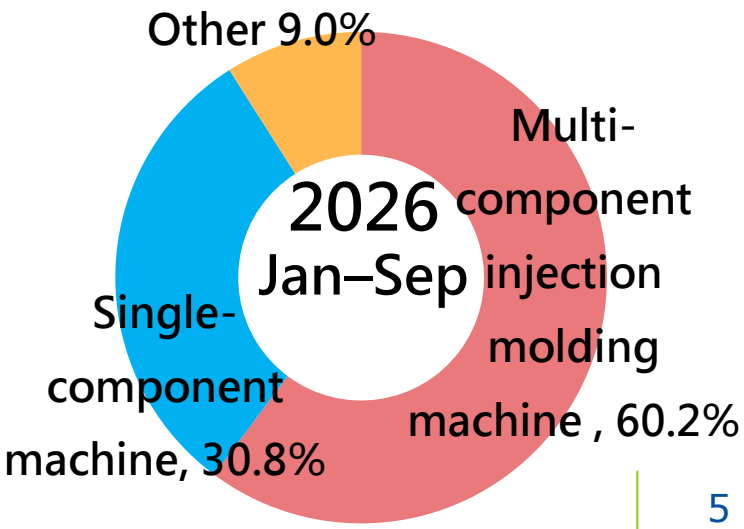
End-Use Applications



Sales by Region



Revenue by Product Category



FCS Key Milestones

Technology Expertise • Global Presence • Smart Transformation • A Sustainable Future

1974

Established FCS Iron Works

Laid the foundation in precision machinery manufacturing



1978

Entered the Plastic Injection Molding Machine Business

Became a specialized injection molding machine manufacturer



1991

Renamed as FCS

Established a clearer corporate brand image



2004

Listed on the Taiwan Stock Exchange (6603)

Officially entered the capital market



2010

Brand Upgrade to a Solution Provider

Providing integrated injection molding solutions



2019

Established Global Production Bases and Sales Network

Over 50 service locations worldwide



2020

Promoted Smart Manufacturing and Industrial 4.0

Built smart factories and integrated plant solutions



2026

Accelerate Smart Transformation for a Sustainable Future

AI-driven smart manufacturing, automotive semiconductor, and sustainable material integrated solutions



FCS Development in Three Stages

Stage 1 : Entrepreneurship and Foundation (1974–1990)

- Established FCS Iron Works
- Entered the plastic injection molding industry
- Built a foundation in the Taiwan market



Stage 2 : Global Expansion (1991–2019)

- Renamed as FCS
- Established global production bases and a sales network
- Listed on the Taiwan Stock Exchange (6603)
- Built a global marketing and service system



Stage 3 : Smart Transformation and a Sustainable Future (2020–Present)

- Advance Smart Manufacturing (Industry 4.0)
- Deepen global market presence
- Focus on AI, smart manufacturing, and sustainable development



Five Global Production Bases

Technology Expertise • Global Presence • Smart Transformation • A Sustainable Future

Business Unit / Item	FCS Taiwan	FCS Dongguan (China)	FCS Ningbo Jiangbei (China)	FCS Ningbo Qianwan (New Plant, China)	FCS India
Product Positioning	Smart manufacturing plant planiing Semiconductor equipment Dedicated equipmerrt for sustiahable materials All-ddicats indtiines molding machines	Multi-component injection molding machines Single-color injection molding machines ICT-dedicated machines	Automotive component injection molding machines Large multi-component injection molding machines	Automotive component injection molding machines Large multi-component injection molding machines Ultra large multi-component injection molding machines	Automotive component injection molding machines Single-color injection molding machines
Sales Markets	Taiwan and overseas markets	South China (Mainland China)	East China (Mainland China)	East China and North China (Mainland China)	India

FCS Taiwan Plant



- Smart manufacturing and R&D kaadquarters
- High-ulive, innovative product development

FCS Dongguan Plant



- Production and supply center for South China
- Fast delivery with a diversified product portfolio

FCS Ningbo Jiangbei Plant



- Production and supply base for Eact China
- Specialization in automotive and large-format products

FCS Ningbo Qianwan Plant (New Plant)



- High-and multi-component machine production base
- R&D and manufacturing of ultra-large equipment

FCS India Plant



- Local manufacturing in India
- Fast delivery and comprehensive service support

Global Presence
Coordinated operations across five production bases

Local Manufacturing
Higher efficiency and faster response to market needs

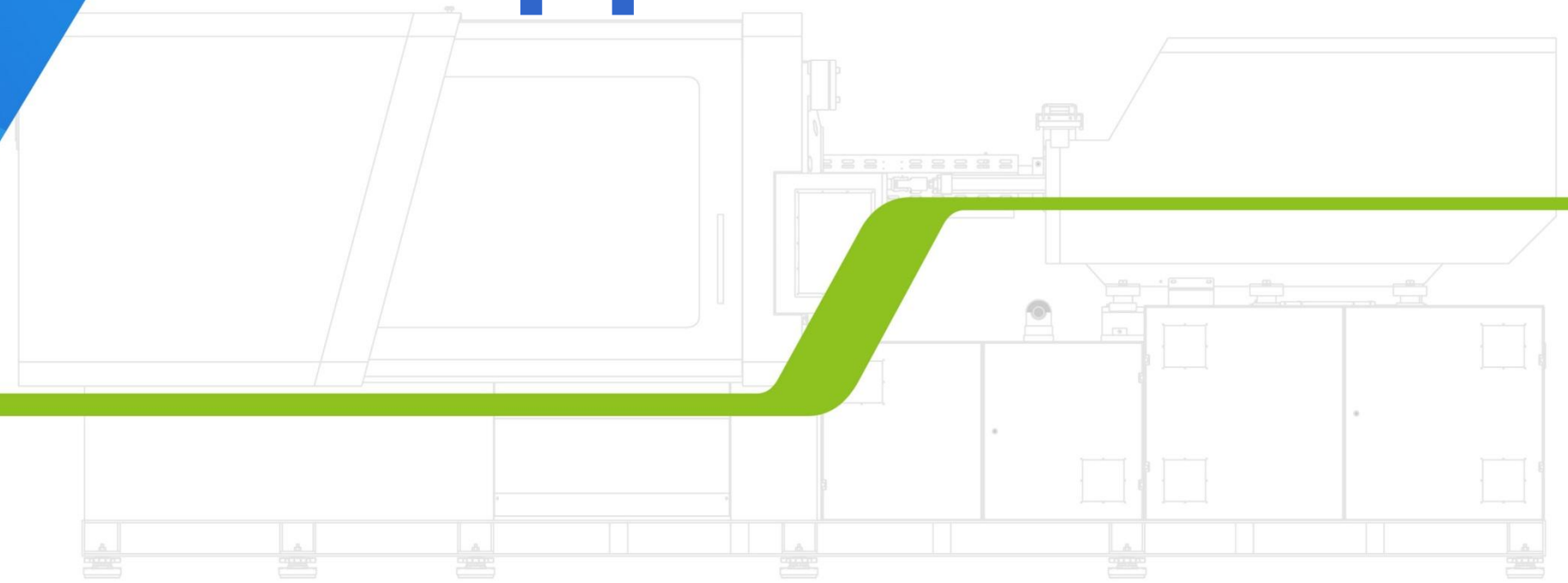
Technology Leadership
Continuous innovation to create competitive advantages

Sustainable Development
Green manufacturing for a shared sustainable feture

FCS
www.fcs.com.tw

PART 02

Market Opportunities



Global Supply Chain Relocation Drives Essential Equipment Demand

Mainland China +1, U.S.–Mexico Manufacturing, and Southeast Asian Expansion: FCS Equipment Leads Every New Factory Setup

Vietnam / Southeast Asia

- Import restrictions on used equipment drive replacement demand.
- Vietnam's revenue reached **NT$400 million in 2025**.

U.S.–Mexico Supply Chain

- New factory construction by customers drives demand for high-end machinery.
- Mexico case: **All-Electric and Multi-Component Injection Molding Machines.**

North American Market Access

- **Unisol,** a major publicly listed Japanese company.
- Development of North American distributors and customers.

FCS Is More Than a Machine Supplier —
A Partner for Solving Complex Manufacturing Challenges

1



Multi-Component Molding Machines

Revenue share: **60%**

Clamping force up to **3,500 tons**, enabling complex exterior parts and Advanced applications.

2



MuCell Physical Foaming Technology

Shipments of nearly NT$100 million last year

Expected to grow 100% this year, driving lightweight solutions and carbon reduction.

3



iMF 4.0

Over 1,000 installations worldwide

Extending from one-time machine sales to data, maintenance, and sustainable service revenue.

Leadership in Multi-Component Molding: Market and Technology Advantages

01 Market Leadership

New energy vehicle multi-component machines hold **over 60%** market share.

02 Technology Leadership

The first company in China to establish a standard unit price for "multi-component molding equipment and mold wear testing."

03 Major Customer Track Record

Six of the World's Top Eight Automative Lighting manufaturers are FCS Customers.

04 Integrated Solution Advantage

Integrates injection molding machines, molds, and smart peripherals with molding technology to provide a one-stop service from customized design to complete factory delivery.

iMF4.0: Driving the Growth of Industrial SaaS



Thousands of Industrial Data Points

×



AI
Quality Monitoring & Predictive Maintenance

×



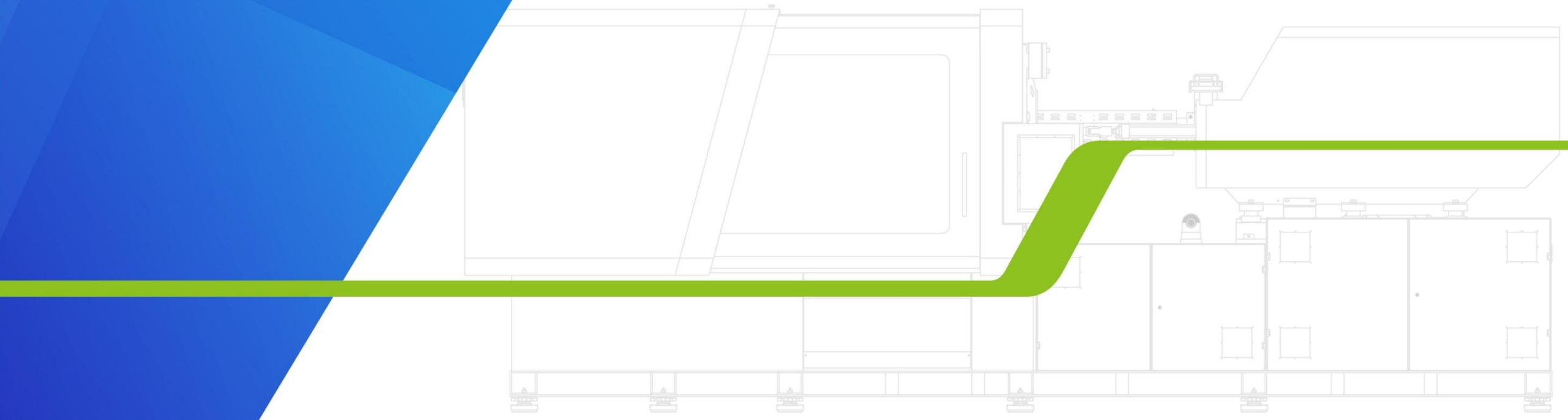
Sustainable Service Revenue



iMF 4.0 has been installed on **over 1,000** customer machines worldwide, providing cloud and edge data platforms with subscription and rental service models.

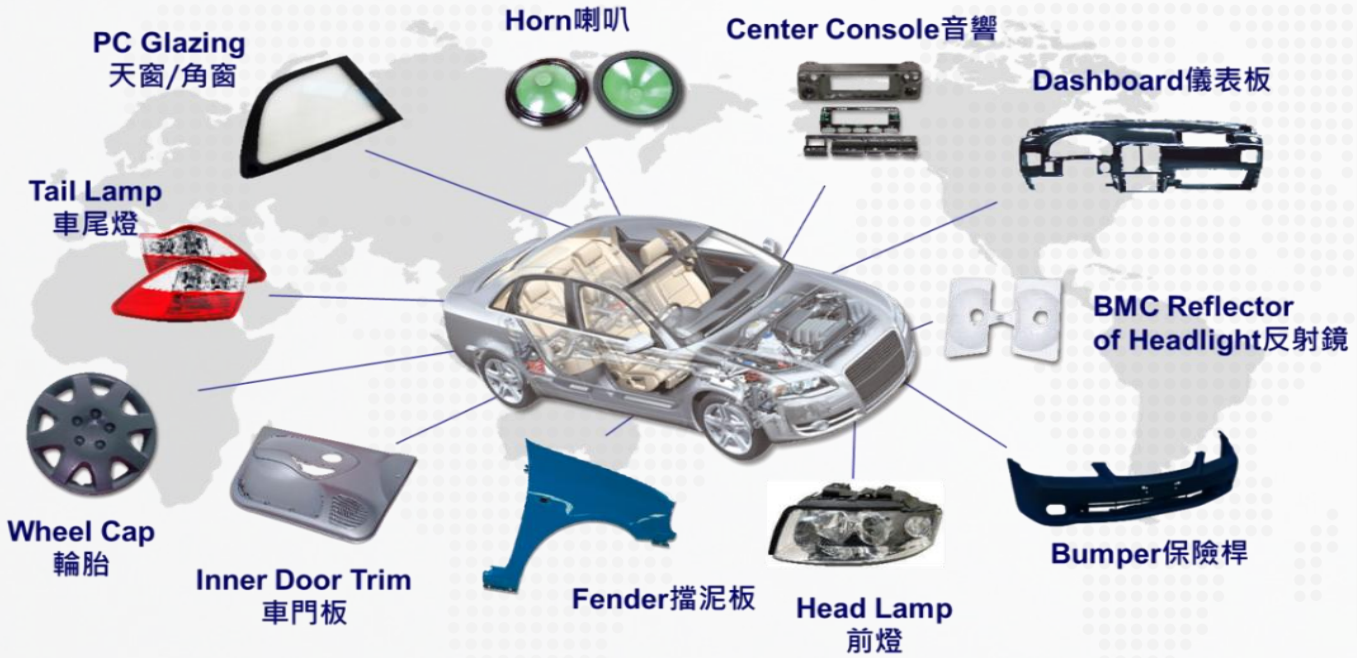
PART 03

Products & Customers



Global indicator customer

Automobile parts – Revenue 50.0% (Q1-Q3 2026)

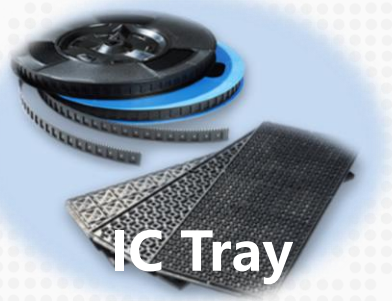


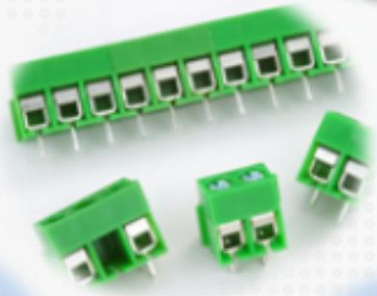
Global indicator customer

Sports industry / ICT products– Revenue 23.4% (Q1-Q3 2026)















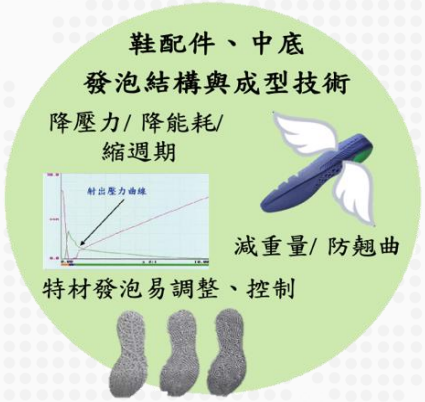
家登精密 Gudeng Precision
FOXCONN 富士康科技集團
PEGATRON 和碩聯合科技
日月光集團
華塑企業 HWA SHU ENTERPRISE CO., LTD.
DELTA
士林電機 ShiLin Electric
Panasonic
泰金寶電通 Cal-Comp Electronics & Communicatio
Canon
LUXSHARE ICT 立讯精密

Global indicator customer

Sports & Consumer – Revenue 22.3% (Q1-Q3 2026)













adidas

NIKE

豐泰企業

framas

DECATHLON 迪卡儂

GIANT GROUP

CIRCLE

TAROKO 昇明國際

CONVERSE

Global indicator customer

Infrastructure – Revenue 3.2% (Q1-Q3 2026)



Automated Warehousing





Construction Materials





Pipes / Valves



南亞

日本積水 SEKISUI

SH

越南 HOA SEN GROUP

Uni-Soleil 應誠

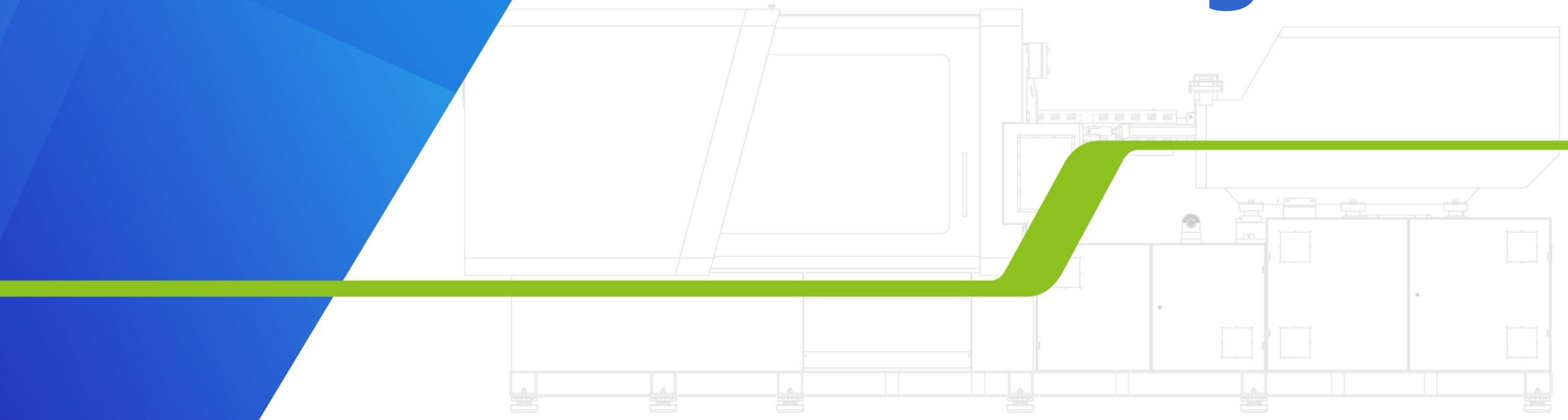
BIN TALEB

印度 Supreme People who know plastics best

Shaheen 沙烏地阿拉伯

PART 04

Competitive Advantages



Turnkey Capability: From Customized Design to Complete Turnkey Solution

Leveraging Our Extensive Integration Experience to Provide One-Stop, Value-Added Services for Injection Molding Machines, Molds, Smart Peripherals, and Molding Technologies

Understand Customer Needs

Plant Layout Design

Quotation & Proposal

Product Design

Equipment Development

Integration Test

Installation & Training

Confirmation & Close





Turnkey Solution Case: New Energy Vehicles



Location
Guangdong, China

Application
Automotive Lighting

Capacity
178 Machines

Annual Output
230,000 Tons

Gaming Keycap – Multi-Color Molding & Pad Printing Application

FCS

Capcity
18 Machines

Annoal Output
50,000 tons

China (Shenzhen)

Gaming Keycap

Application Video

Turnkey Solution Case:
A Leading German Footwear Manufacturer

framas® indonesia







Location
Indonesia

Industry
Footwear

A Turnkey Solution for a Leading German Footwear Brand

Integrating footwear technology with injection molding to build a complete production facility.

Turnkey Solution Case:

India Turnkey project for Leading Toy OEM Supplier to U.S. and European Brands





Location	India (Bangalore)
Number of Machines	220 Units
Clamping Force	40,000 Tons

India Turnkey project for Leading Toy OEM Supplier to U.S. and European Brands

Turnkey Solution Case:
A Major Infrastructure in Vietnam





Location	Ho Chi Minh City, Vietnam
Number of Machines	30 Units
Clamping Force	120,000 Tons

A Key Infrastructure in Vietnam

Home to 40 of the world's most valuable brands, 11 large-scale factories, and nearly 300 sales outlets across the country.

Turnkey Solution Case:
A Leading Taiwanese Electronics Manufacturer





Location | Vietnam

Number of Machines | 15 All-Electric Injection Molding Machines

Clamping Force | 3,000 Tons (0.3 Million Tons)



A Turnkey Solution for a Leading Taiwanese Electronics Manufacturer

Turnkey Solution Case:
FIH Mobile Limited





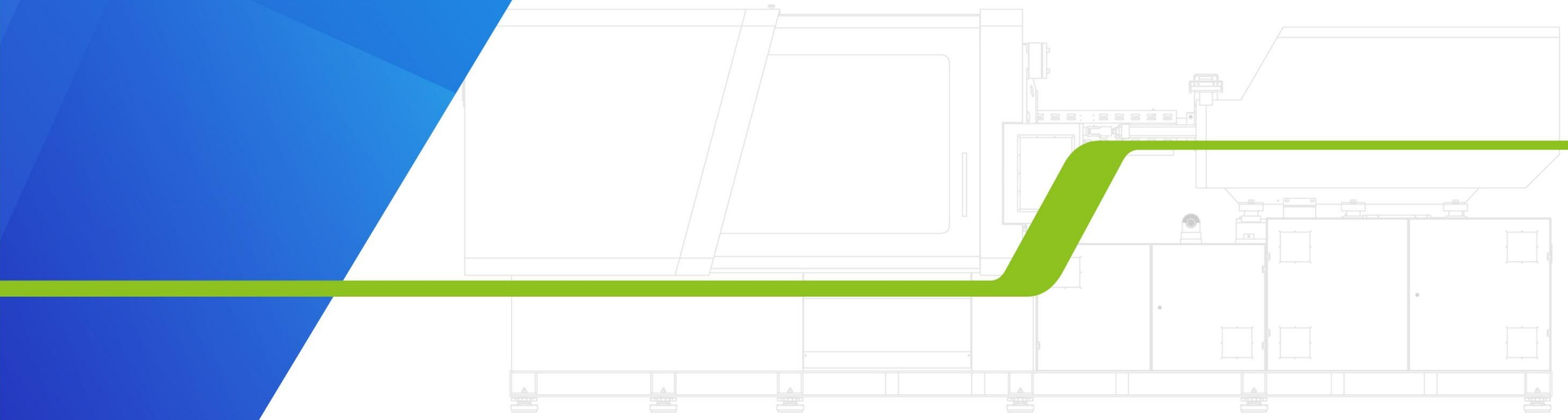
Location	Chihuahua, Mexico
Number of Machines	14 All-Electric + 2 Two-Color Injection Molding Machines
Clamping Force	4,000 Tons (0.4 Million Tons)



A Turnkey Solution for Fuchikang Group

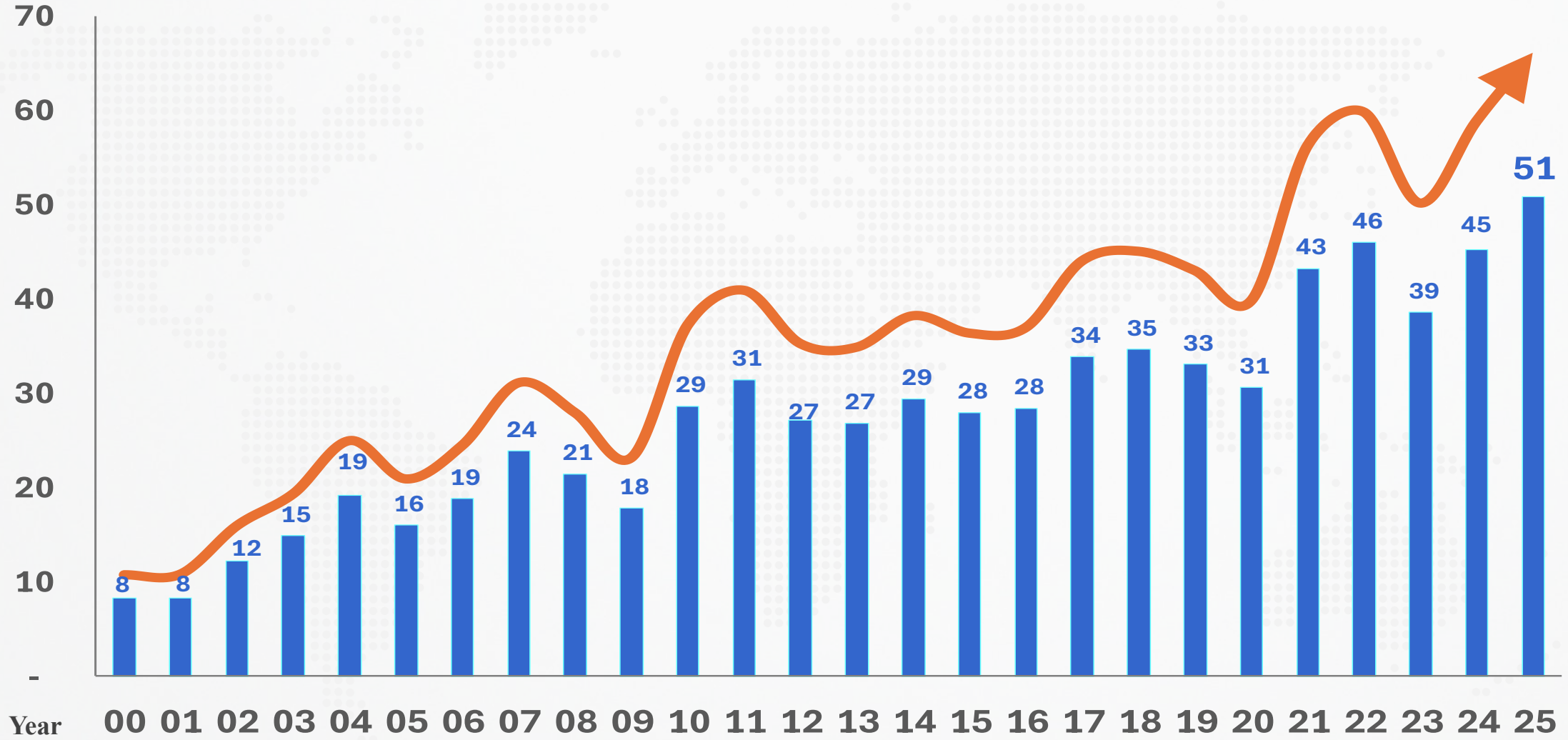
PART 05

Business Review



Revenue growth

Unit: NTD 100 million



Combined profit and loss statement

Unit: NTD thousand

Item\Year	2024	2025	YOY	2025 Q3	2026 Q3	YOY
Operating revenue	4,529,411	5,082,840	12.22%	3,630,706	3,418,993	-5.83%
Operating costs	3,369,271	3,795,423	12.65%	2,706,720	2,565,246	-5.23%
Gross operating profit	1,160,140	1,287,417	10.97%	923,986	853,747	-7.6%
Gross profit margin	25.61%	25.33%	-0.28%	25.45%	24.97%	-0.48%
Operating expenses	1,039,567	1,082,496	4.13%	789,910	784,026	-0.74%
Operating profit	120,573	204,921	69.96%	134,076	69,721	-48.0%
Operating profit margin	2.66%	4.03%	1.37%	3.69%	2.04%	-1.65%
Net non-operational income (expenditure)	11,611	-29,197	-351.46%	-40,907	1,189	-102.91%
Consolidated net profit before tax	132,184	175,724	32.94%	93,169	70,910	-23.89%
Income tax (expense)	60,079	65,864	9.63%	41,048	31,481	-23.31%
Consolidated net profit after tax	72,105	109,860	52.36%	52,121	39,429	-24.35%
Net profit attributable to the parent company after tax	78,765	100,474	27.56%	44,888	36,607	-18.45%
EPS (NTD)	0.50	0.61	22.0%	0.27	0.22	-18.52%

Consolidated Balance Sheet

Unit: NTD thousand

Accounting item \ Year	2025.12.31		2025.9.30		2026.9.30	
	Amount	%	Amount	%	Amount	%
Cash and financial assets	960,102	11.3	998,364	12.1	1,096,854	12.5
Accounts receivable	2,229,057	26.2	2,036,356	24.6	2,134,026	24.2
Inventory	1,967,262	23.1	2,070,514	25.1	2,255,261	25.6
Other current assets	321,671	3.8	206,899	2.5	215,816	2.5
Real estate property, plant and equipment, net investment-based real estate property	2,146,408	25.2	2,069,162	25.0	2,210,359	25.1
Other non-current assets	884,327	10.4	882,995	10.7	890,860	10.1
Total assets	8,508,827	100.0	8,264,290	100.0	8,803,176	100.0
Current liabilities	3,184,213	37.4	3,143,842	38.0	3,389,337	38.5
Non-current liabilities	2,570,154	30.2	2,578,404	31.2	2,547,837	28.9
Total liabilities	5,754,367	67.6	5,722,246	69.2	5,937,174	67.4
Total shareholders' equity	2,754,460	32.4	2,542,044	30.8	2,866,002	32.6
Net value per share (NTD)	15.47		14.28		16.13	

Consolidated Statement of Cash Flows

Unit: NTD thousand

Item	2025.9.30	2026.9.30	Difference in amount	Difference%
Cash and equivalent cash balance at beginning of period	676,230	904,248	228,018	33.72
Net cash inflow (outflow) from operating activities	-88,013	201,299	289,312	-328.72
Net cash inflow (outflow) from investing activities	-3,507	-16,442	-12,935	368.83
Net cash inflows (outflows) from financing activities	302,298	15,995	-286,303	-94.71
Effect of exchange rate changes on cash and equivalent cash	58,048	-24,751	-82,799	-142.64
(Decrease) in cash and equivalent cash for the current period	268,826	176,101	-92,725	-34.49
Cash and equivalent cash balance at end of period	945,056	1,080,349	135,293	14.32

Financial ratio analysis

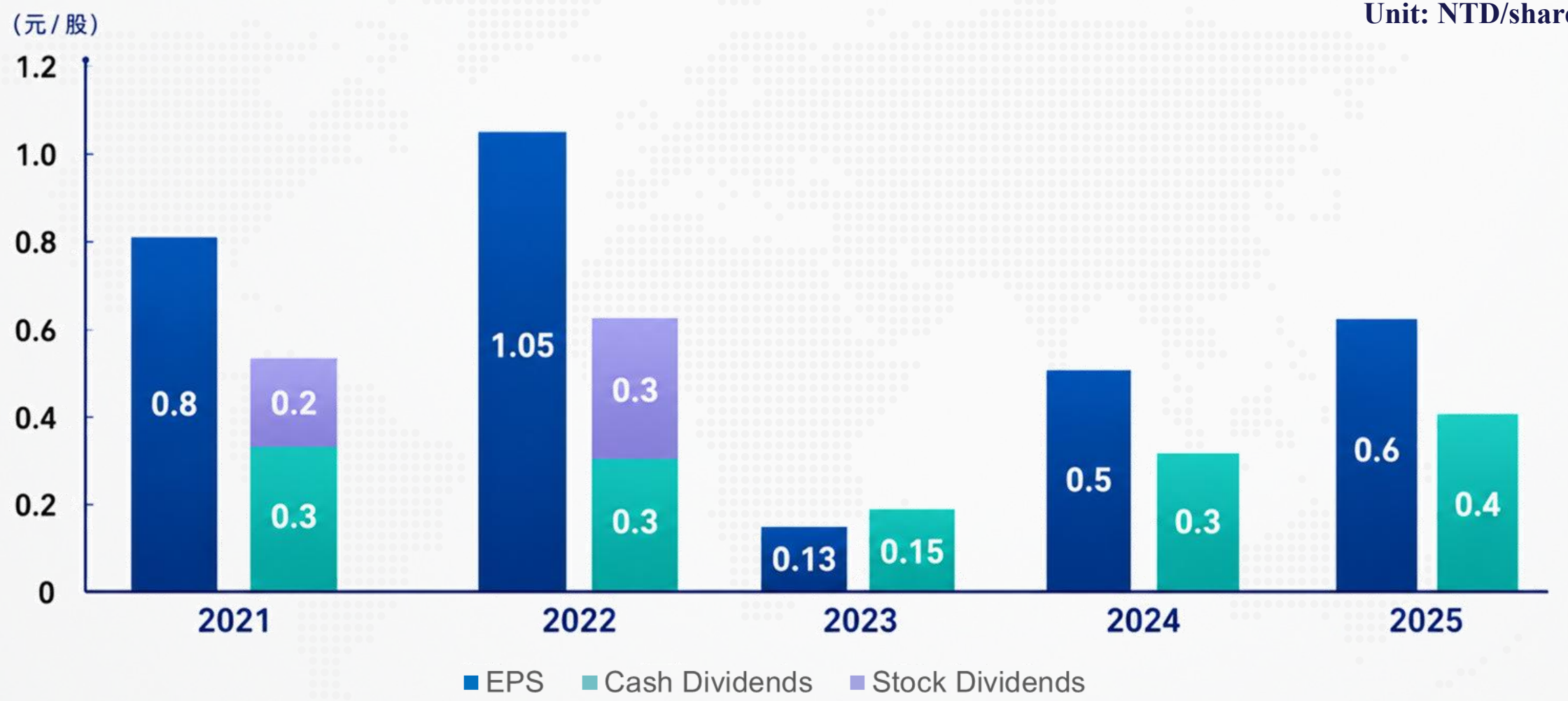
Unit: NTD thousand

Item	Year	2025.9.30	2026.9.30	2025.9.30 v.s. 2026.9.30
Financial structure %	Liabilities to assets ratio (%)	9.24	67.44	-1.8
Repayment ability %	Current ratio (%)	168.97	168.23	-0.74
	Quick ratio (%)	103.11	101.69	-1.42
Business capability	Receivables turnover ratio (times)	0.72	0.62	-0.1
	Inventory turnover (times)	0.49	0.4	-0.09
Profitability	Return on assets (%)	10.67	0.16	-10.51
	Return on equity (%)	2.19	0.49	-1.7
	Net profit margin (%)	3.97	1.21	-2.76
	Net profit margin (%)N	0.27	0.22	-0.05

Dividend Policy

The average interest rate over the past five years is 64%

Unit: NTD/share



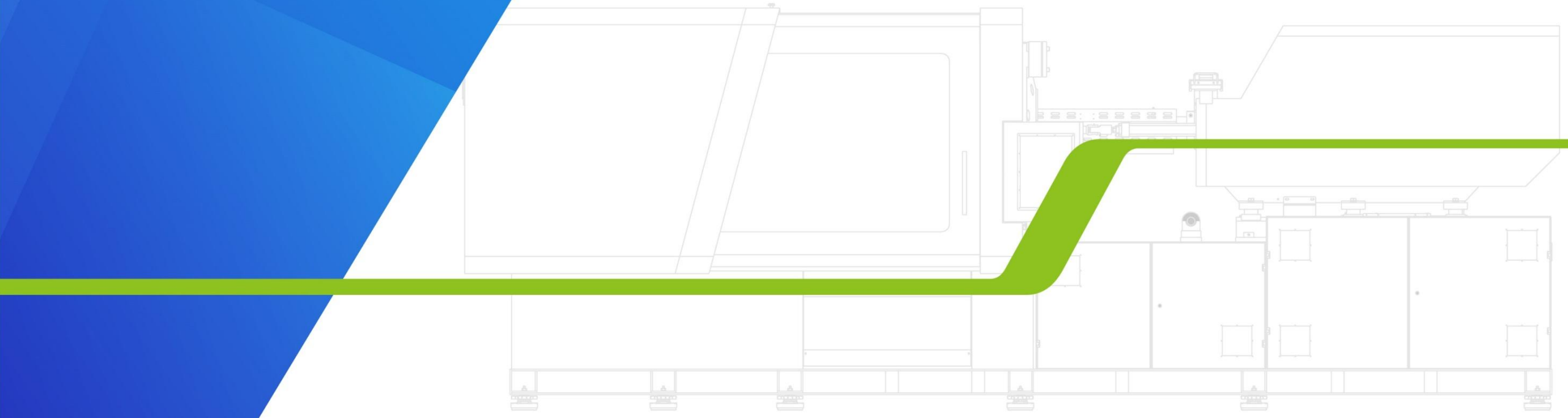
Exhibition highlights

Exhibition: 4 exhibitions will be held worldwide in 2026

Month	Country/Location	Exhibition Name
November	• Mexico/Mexico City • Indonesia/Jakarta	• Plastimagen • PRI
December	• China/Shenzhen • Türkiye/Istanbul	• DMP • Plast Eurasia Istanbul

PART 06

Next Growth Curve



Dual-Track Strategy in Semiconductors, Accelerating the Group's Second Growth Curve

Targeting the **Advanced MLPC** and **AI substrate** markets, we combine **high-precision components** and **equipment agency**, with a dual-track approach spanning **AI / HPC** advanced packaging to deliver a complete **supply chain.**

Existing Core

Precision Injection Molding Machines + Smart Manufacturing



- Global Deployment with Proven Results
- Software Services for Synchronized Upgrade

Growth Engine A

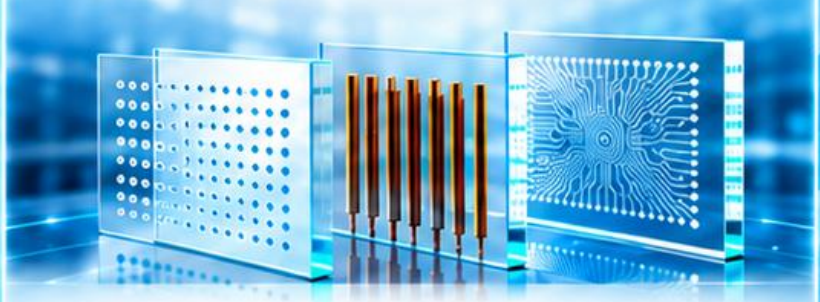
Advanced MLPC New Business



- GPU Inductors / Decoupling
- AI Servers / AI PCs
- Process & AI-Related Electronic Components

Growth Engine B

Advanced Packaging Key Equipment



- AI Substrates (Glass Substrates)
- TGV / VP / VCP
- Advanced Packaging Key Equipment

AI Key Components + Advanced Packaging Equipment

FCS | GROWTH ENGINE A

Advanced MLPC:
Investment Plan & Market Outlook

- Production Base: FCS AI Manufacturing Base (Building V)
- Phase I Investment: **NT$ 200 Million**
- Market Demand: **6 Billion** Units per Year,
- FCS Target Market Share: **90% Japamese Supplier Market share , High Substitution Potential**



Source: Economic Daily News, Sep. 7, 2026

MLPC: A Key Growth Driver for Solid-State Capacitors

Upgrading AI Servers to Drive High-End Capacitor Demand and Initiate a New Long-Term Growth Engine

1. AI Servers Driving Advanced Capacitor Upgrade



- AI server power consumption continues to rise
- Demand for Advanced **MLCC** and **MLPC** is growing in step
- High capacitance, high voltage, and low ESR become key specifications
- VRM power modules drive upgrade demand

2. Core Advantages of MLPC (Solid-State Capacitors)

High Capacitance & High Voltage	• Support high current and high power for AI applications
Low ESR & Low Heat	• Increase power efficiency • Reduce system temperature
Long Service Life & High Reliability	• Suitable for long-term operation of AI servers
Stable Power Supply	• Enhance the stability of GPU / CPU power systems

3. Expanding Application Markets

- AI Server
- GPU Accelerator Card
- Automotive Electronics (800V High-Voltage Platform)
- Industrial Power Supply
- 5G Communication Infrastructure
- High-Performance Computing (HPC)

MLPC (Solid-State Capacitors) Are Being Widely Adopted Across Multiple High-Growth Domains

4. Market Development Trend

AI Applications Accelerate	Power Demand Keeps Rising	Solid-State Capacitors Penetrate Further	Higher Reliability Demand Grows
AI + HPC drive rapid growth in high-power needs	VRM upgrades require more efficient capacitors	MLPC advantages become clearer, with rising penetration	Longer service life and higher reliability become key competitiveness

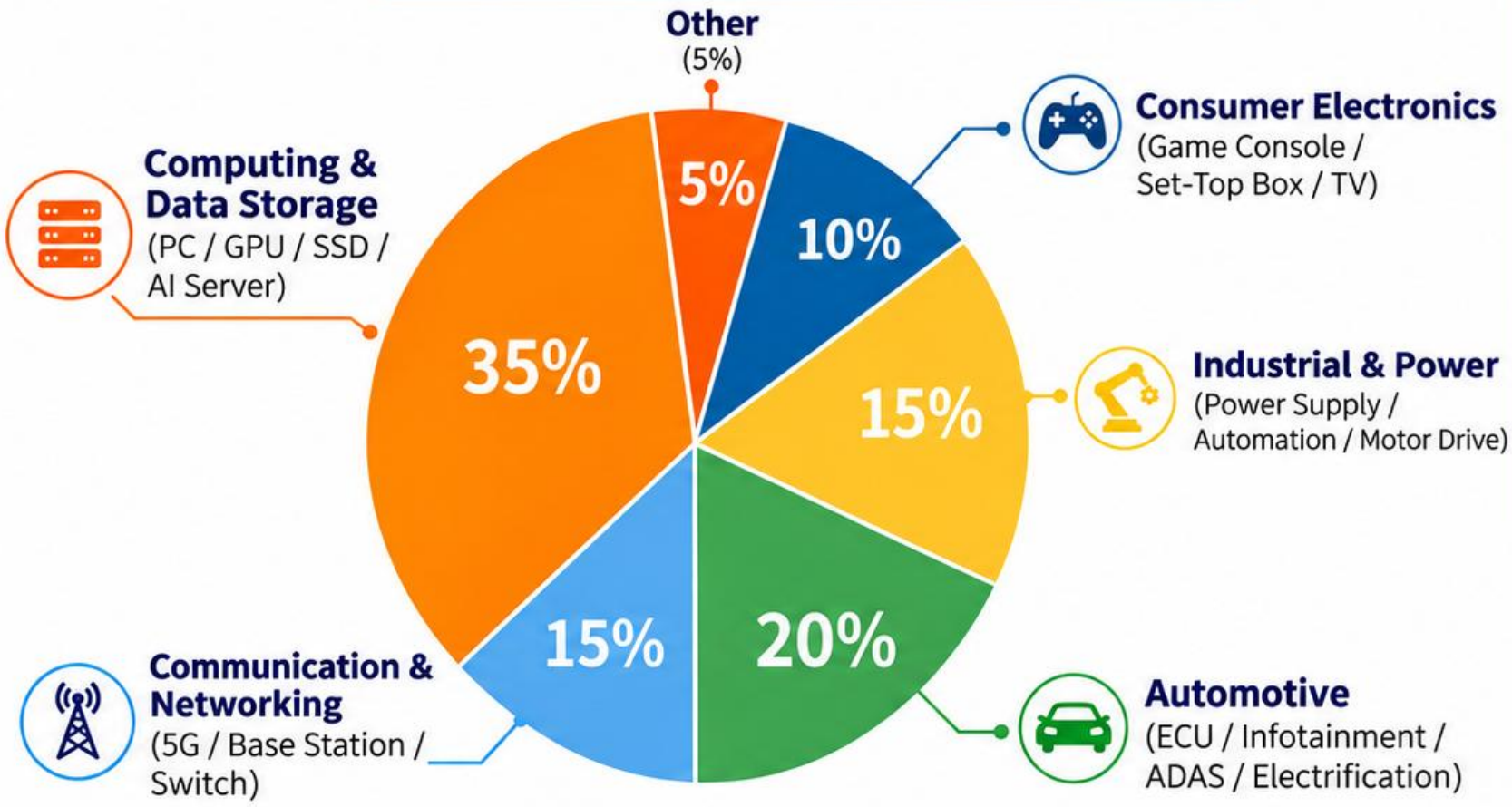
5. FCS Strategic Focus

- Focus on AI server, GPU, and high-power power supply markets
- Develop high-capacitance, low-ESR, high-voltage MLPCs (solid-state capacitors)
- Build high-reliability product design and smart manufacturing capabilities
- Capture AI power upgrade opportunities and import substitution demand

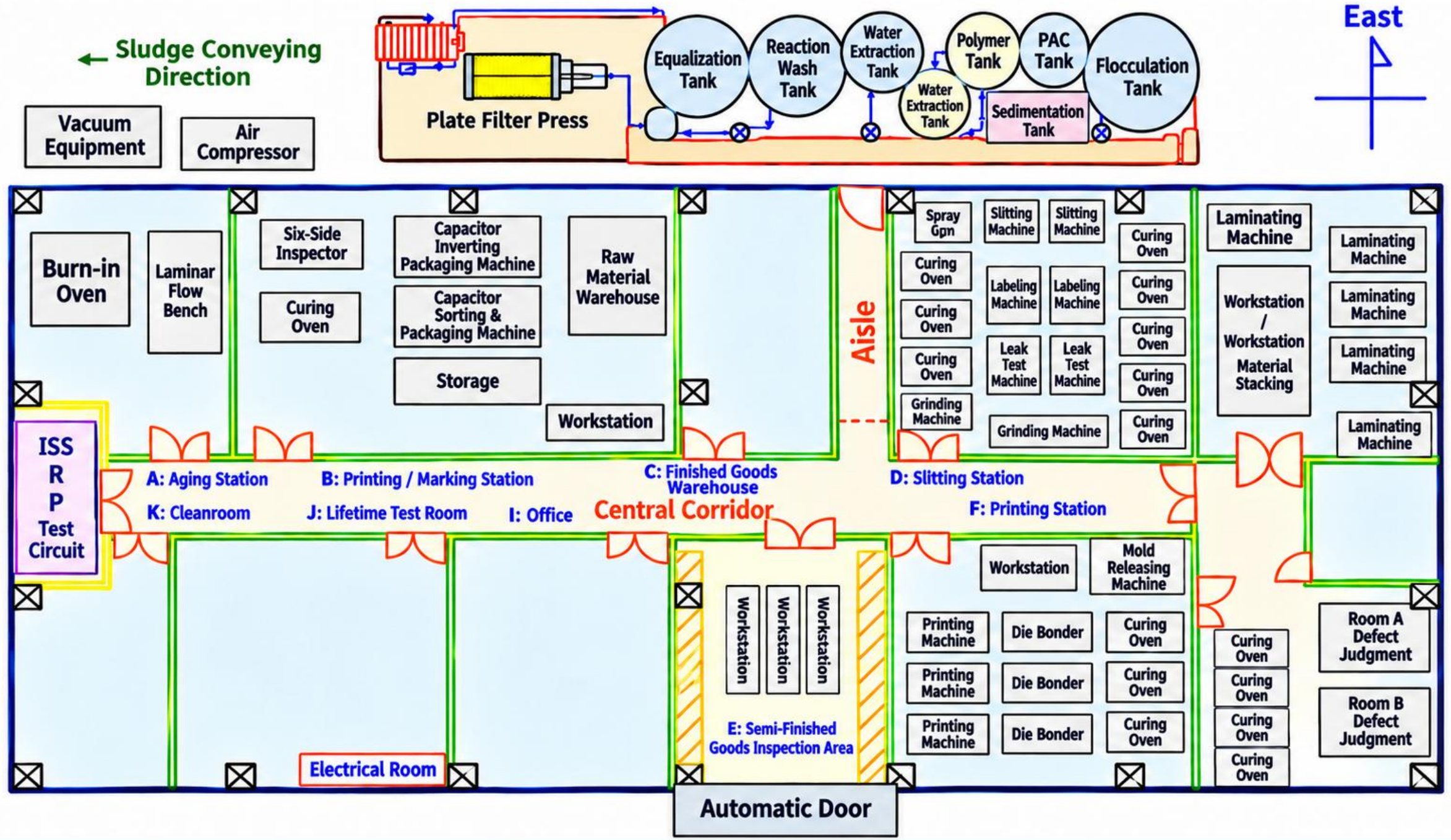
Expanding AI Applications × Power Upgrades × Higher Reliability →
Continuously Driving MLPC (Solid-State Capacitors) as a Key Growth Engine in the AI Supply Chain.

Application Market Distribution

MLPC Application Industry Distribution

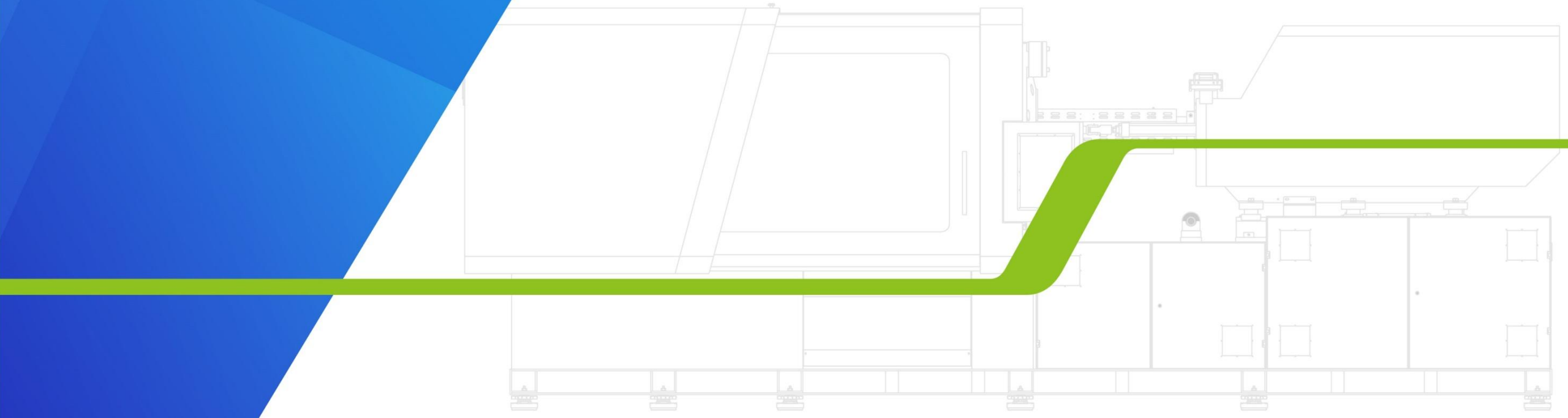





Sludge Conveying Direction
Vacuum Equipment
Air Compressor
Plate Filter Press
Equalization Tank
Reaction Wash Tank
Water Extraction Tank
Water Extraction Tank
Polymer Tank
PAC Tank
Flocculation Tank
Sedimentation Tank
East
Burn-in Oven
Laminar Flow Bench
Six-Side Inspector
Curing Oven
Capacitor Inverting Packaging Machine
Capacitor Sorting & Packaging Machine
Storage
Raw Material Warehouse
Workstation
Aisle
Spray Gpn
Curing Oven
Curing Oven
Curing Oven
Grinding Machine
Slitting Machine
Slitting Machine
Labeling Machine
Labeling Machine
Leak Test Machine
Leak Test Machine
Grinding Machine
Curing Oven
Curing Oven
Curing Oven
Curing Oven
Curing Oven
Laminating Machine
Workstation / Workstation Material Stacking
Laminating Machine
Laminating Machine
Laminating Machine
Laminating Machine
ISS R P Test Circuit
A: Aging Station
B: Printing / Marking Station
C: Finished Goods Warehouse
D: Slitting Station
K: Cleanroom
J: Lifetime Test Room
I: Office
Central Corridor
F: Printing Station
Workstation
Workstation
Workstation
E: Semi-Finished Goods Inspection Area
Workstation
Mold Releasing Machine
Printing Machine
Printing Machine
Printing Machine
Die Bonder
Die Bonder
Die Bonder
Curing Oven
Curing Oven
Curing Oven
Curing Oven
Curing Oven
Curing Oven
Curing Oven
Room A Defect Judgment
Room B Defect Judgment
Electrical Room
Automatic Door

PART 06

Next Growth Curve



FCS | GROWTH ENGINE B

AI-Driven CoWoS Advanced Packaging Upgrade

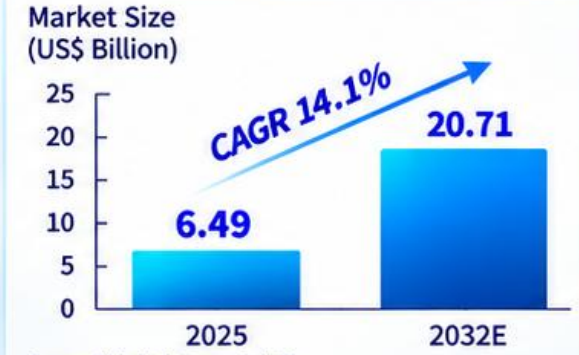
AI / HPC Drives High-End PCB Demand, Substrate Generational Upgrade, and Continued Advancement of Plating Processes

Global PCB Market



Source: Prismark, Q1 2026.

ABF Substrate (FC-BGA)



Source: Global Info Research (GIR),
"Global ABF (Ajinomoto Build-up Film) Substrate Market 2026," Jul. 2026.

1 ABF Area Expansion and CoWoS Packaging Challenges

Capacity Ramp-Up Effect

With the rapid growth of large AI models (e.g., NVIDIA Blackwell and Rubin), demand for CoWoS and other advanced packaging technologies is surging, driving a significant increase in ABF substrate area.

Warpage and Thermal Stress Challenges

As the silicon interposer area continues to increase, larger board warpage and thermal stress arise, requiring ABF substrates with higher thickness (more layers) to ensure long-term reliability under high load.

2 Technology Breakthrough: The Rise of Glass Substrate

Overcoming the Physical Limits of Organic Substrates

To address ABF substrate challenges such as size limitations in packaging, warpage, and thermal resistance, the glass substrate is regarded as a revolutionary next-generation material.

Core Advantages

Glass offers ultra-high rigidity, extremely low warpage, superior high-frequency electrical characteristics, and excellent dimensional stability.

Five-Generation Evolution of Packaging Substrates: Material Replacement Drives Plating Process Upgrades

1st Generation: Ceramic Substrate	
1950s–1970s	
Material	Alumina / Aluminum Nitride (AlN)
Packaging	DIP / QFP / PGA
Plating	Simple Through-Hole Plating
Key Feature	Wiring Density < 200 pins

2nd Generation: BT Resin	
1980s–1990s	
Material	BT Resin
Packaging	PBGA / WB-BGA
Plating	VCP (Vertical Continuous Plating) Through-Hole Copper
Key Feature	Line Width > 40 μm

3rd Generation: ABF Build-up Film	
2000s–Present (Mainstream)	
Material	ABF Build-up Film
Packaging	FC-BGA / CoWoS-R
Plating	SAP / mSAP / Microwave Copper Plating
Key Feature	CTE Matching, Low Loss (DF)

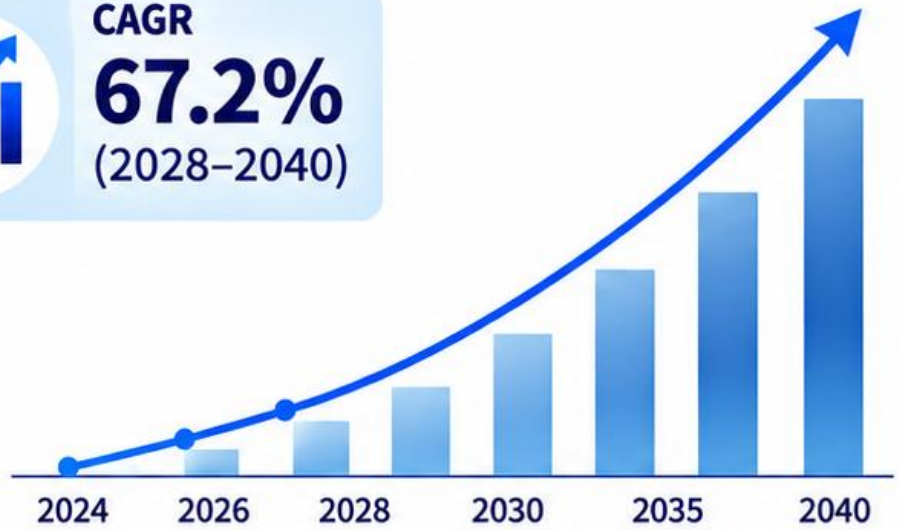
4th Generation: Silicon Interposer	
2010s–Present (2.5D)	
Material	Silicon Interposer
Packaging	TSV + RDL (Redistribution Layer) CoWoS / EMIB
Plating	TSV Aspect Ratio > 10:1
Key Feature	High Cost, Process Complexity

5th Generation: Glass Substrate	
2020s – Commercialization Begins	
Material	TGV + Panel-Level RDL
Packaging	Glass Core / CoPoS
Plating	TGV Copper Filling
Key Feature	Major Manufacturers Actively Investing

Glass Substrate TGV Enters Mass Production in 2028: A Key Milestone

Global Glass Substrate Market Size Forecast

CAGR
67.2%
(2028–2040)



GNC Global Net Corp. | semi™

Source: SEMI · Global Net Corp. (GNC) · Glass Core Substrate Market and Development Trends, 2026.

Global Glass Substrate Market Development Timeline

2025–2027
Technology Validation and Pilot Production

2028
Initial Mass Production (Targeting High-End AI / HPC Applications)

2030+
Accelerated Market Adoption and Broader Applications

2040
Long-Term Growth and Significant Market Potential

Opportunities for Taiwan

Driven by AI / HPC Demand
High-performance computing demand will drive the adoption of advanced packaging, with glass substrates becoming a key solution.

Supply Chain Integration
Leverage Taiwan's advanced packaging and equipment cluster in Central Taiwan to build a local glass substrate supply chain and gain manufacturing advantages.

Equipment / Material / Process Innovation
Enter key areas such as TGV, VP, and VCP equipment, materials, and processes to capture the next wave of growth opportunities.

Higher Density, Larger Form Factor

Lower Warpage, Higher Stability

Superior Thermal Performance to Enable High-Efficiency Applications

FCS – Exclusive Agent for Semiconductor Frontier Equipment from CKST

Obtain exclusive agency rights in Taiwan and Southeast Asia, targeting the semiconductor advanced packaging market.

Taiwan + Southeast Asia
Exclusive agency territory

20–25%
Cost savings in plant construction

Secure Next-Generation Market
AI advanced packaging market

TGV | VP | VCP
Key process equipment

Strategic Technology Partnership

R&D Core in Korea
Core technologies from CKST's leading semiconductor R&D team in Korea

Production Base in Suzhou
Competitive edge in both technical indicators and manufacturing cost

Local Service Network
Integrate service resources in Greater China and Southeast Asia to provide real-time support

From TGV Drilling to Mass-Production Plating Equipment: A Complete Equipment Portfolio

01 | TGV Glass Drilling and Plating-Filling Equipment
High aspect ratio
Void-free (bubble-free) filling

02 | Advanced Vertical Production Equipment – VP
One Bath One Panel
Plating thickness variation ≤ 3%

03 | High-Aspect-Ratio Vertical Continuous Plating Equipment – VCP
High efficiency
Equipment for large-volume mass production

SPP High-Performance Panel Plating Equipment

A comprehensive, advanced panel-level plating solution for multi-size trials, pilot runs, and mass production

CKST
China Korea Smart Technology

ENABLING ADVANCED PACKAGING



01 Equipment Overview

CKST's SPP is a high-performance panel-level plating system for multi-size trials, pilot runs, and mass production. It supports high aspect ratio, large-size glass substrates, enabling **TGV filling**, **copper pillar (Cu-Post) plating**, and **redistribution layer (RDL) plating** with ultra-fine pattern capability. The system also features dedicated process modules for high-uniformity electroless plating and reliability verification, meeting diverse application and R&D needs.

02 Key Advantages

Supports Multi-Size Applications
Suitable for R&D trials and mass production, meeting requirements across different development stages.

Full Process Coverage
Supports TGV filling, Cu-Post, RDL, and other plating processes.

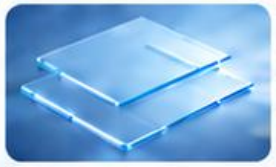
High Precision and Uniformity
Excellent process control and intelligent monitoring to ensure stable, reliable, and high-quality plating.

Fast Qualification and Mass Production Ramp-Up
Supports batch qualification and scalable equipment expansion, shortens process development cycle, and accelerates the transition from trial production to mass production.

03 Key Specifications

1. **< 5 μm**
   Line width / space capability
2. **Uniformity < 3%**
3. **Glass Substrate Processing Capacity**
4. **Panel size**
   515 × 510 mm
5. **TGV aspect ratio ⩾ 10:1**
   (depending on product design)

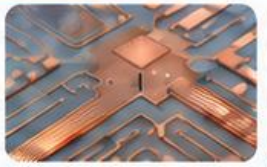
04 Application Areas



TGV
Glass substrate drilling/filling



Cu-Post
Copper pillar plating



RDL
Redistribution layer



High-Value Panel Substrates
Advanced packaging applications

Taiwan-Korea Collaboration for Glass Substrate Equipment

A Technology × Channel Synergy to Capture the AI Advanced Packaging Market

01

FCS (6603) | CKST China Korea Smart Technology

Taiwan–Korea Collaboration to Enter the Glass Substrate (TGV) Market

Leverage Korea's leading glass substrate equipment technology and FCS's market channels to capture new opportunities in AI advanced packaging.

02



Reach Customers and Expand Across Taiwan and Southeast Asia

Adopt TGV / VP / VCP and glass substrate process equipment, enter the Taiwan and Southeast Asia markets, and broaden the customer base.

03



Manufacturing + After-Sales Service

Establish local advantages through equipment manufacturing, automation integration, and global service capabilities to meet customer localized needs and deliver greater value.

04



Secure a Position in AI Advanced Packaging and Accelerate Next-Stage Growth

Use glass substrate equipment as a bridge to integrate into the next-generation advanced packaging supply chain, address AI and HPC chip demand, and create sustainable long-term growth momentum.

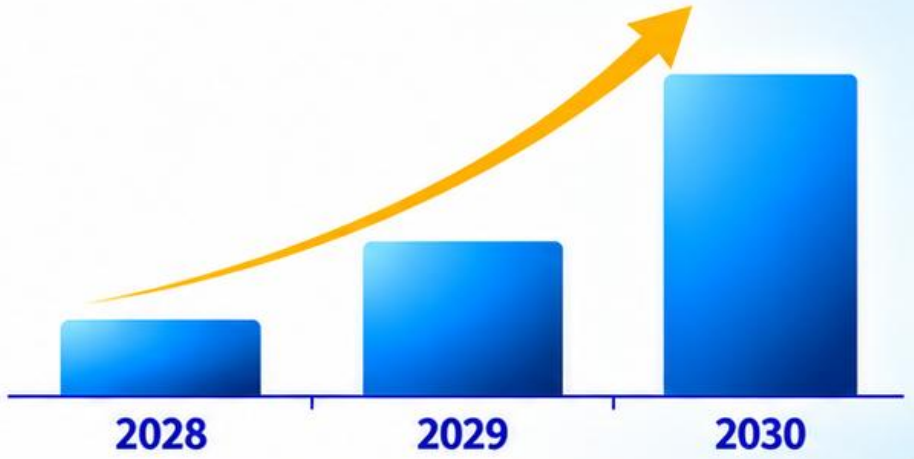
"FCS is not merely an equipment representative, but an industrial partner with equipment manufacturing, automation integration, and global service capabilities."

FCS – TGV Equipment Market Outlook for Glass Substrates

Capture the Advanced Packaging Trend and Accelerate Next-Stage Growth

Year	TGV Market Value (NT$100 Million)	Share of Equipment Market Value	Equipment Demand (NT$100 Million)
2028	300	80%	240
2029	1,500	35%	525
2030	2,400	35%	840

Sales Forecast



Enter the AI Advanced Packaging Supply Chain

Rapid Growth in Equipment Demand

Accelerate the Semiconductor Next-Stage Growth Engine

Future Outlook

01 Increase AI Revenue Share

- Deploy semiconductor-related components and advanced packaging markets
- Expand into power electronics and high-efficiency energy applications
- Drive customers to adopt comprehensive smart factory solutions
- Strengthen AI applications and digital services

02 Improve Profitability

- Continuously improve gross margin and operational efficiency
- Increase ROE and operating cash flow
- Enhance global operations management

Become a Global Leading Brand for Smart Injection Forming and Smart Manufacturing Solutions

03 Global Market Growth

- Penetrate in Taiwan, Southeast Asia, and the Americas
- Expand global service locations
- Increase overseas revenue share

04 Sustainable Operation (ESG)

- Drive low-carbon manufacturing
- Advance a circular economy and resource efficiency
- Build a smart factory and a green supply chain

Global Deployment
Collaborate across five major production bases

Local Manufacturing
Improve efficiency and rapidly meet market demand

Technology Leadership
Drive continuous innovation and build competitive advantages

Sustainable Development
Green manufacturing, shared value for a better future

FCS
www.fcs.com.tw

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